

ABLATION METHOD FOR DIE ATTACH FILM

ABSTRACT OF THE DISCLOSURE

An ablation method of applying a laser beam to a die attach film to perform ablation. The ablation method includes a protective film forming step of applying a liquid resin containing a fine powder of oxide having absorptivity to the wavelength of the laser beam to at least a subject area of the die attach film to be ablated, thereby forming a protective film containing the fine powder on at least the subject area of the die attach film, and a laser processing step of applying the laser beam to the subject area coated with the protective film, thereby performing ablation through the protective film to the subject area of the die attach film after performing the protective film forming step.

(FIG. 5)